

PRINTED CIRCUIT BOARDS**ABSTRACT**

This invention is to provide a printed circuit board suitable for the high densification of mounting parts using a solder bump and for the improvements of connection reliability and mounting reliability, and proposes a printed circuit board having a structure of alternately a laminating conductor circuits and interlaminar insulating layersprinted circuit board, characterized in that the interlaminar insulating layer insulating between a surface layer of conductor circuit and an inner layer of conductor circuit is provided with an opening exposing the inner layer of conductor circuit and a viahole made from a metal film electrically connecting the surface layer of conductor circuit to the inner layer of conductor circuit and a solder bump is filled and formed in the viahole.

Figure 3